

REMARKS

A revised claim 1 is provided herein. It was noted following filing of the June 5, 2002, Amendment that the underlining of the newly added term "50" in line 6 of the claim was inadvertently omitted from the marked-up version of the claim. This term is underlined in the marked-up version of the claim attached hereto.

The presently submitted claim 1 is submitted to comply with 37 C.F.R. § 1.121 and entry of this amended claim 1 is requested prior to consideration of the remarks filed in the June 5, 2002 Amendment.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

Please amend claim 1 as follows:

1. A wiring board for a semiconductor device, comprising:

a predetermined wiring section being disposed on an insulation board; and

an electromagnetic shielding film being placed at a position close to said wiring

section,

wherein a distance defined between, said wiring section and said electromagnetic shielding film is [150] 50 μm or less, a volume specific resistance of said electromagnetic shielding film is $30 \mu\Omega\cdot\text{cm}$ or less at room temperature, and

wherein, over an applicable frequency between about 10MHz to 15GHz, and
inductance of said wiring section and inductive cross talk are reduced.